



OCP-IP AND ECSI ANNOUNCE COLLABORATION

PORTLAND, Ore. — April 5, 2004— Open Core Protocol International Partnership (OCP-IP) and European Electronic Chips & Systems Design Initiative (ECSI) announce a collaboration between the two respective organizations. The agreement allows the industry organizations to work in partnership and provide a greater awareness of the direction and initiative for each organization to their respective memberships.

OCP-IP provides a common standard for intellectual property core interfaces, or sockets, that facilitate “plug and play” SoC design, and ECSI is the organization developing and promoting efficient methods for electronic systems design, with particular regards to the needs of the system-on-chip.

ECSI’s goal is to provide members with a competitive advantage for the benefit of the European industry. The value in a relationship with ECSI for OCP-IP is wider reach in the European market. The agreement also allows for a closer collaboration and synergy with the two organizations. For ECSI, the collaboration signifies further support for open technologies.

“ECSI’s mission is to identify, develop and promote efficient methods for electronic systems design, with particular regards to the needs of the system-on-chip,” said Adam Morawiec, president of ECSI. “OCP-IP supports those same goals by standardization of SoC IP interfaces. Collaboration by both organizations will greatly benefit the industry as a whole.”

“OCP-IP is leading the way in openness, collaborations and working together through initiatives that serve the common good of the industry,” said Ian Mackintosh, president of OCP-IP. “ECSI’s extensive training program and broad European membership will ensure improved sharing of information, help us better communicate with our individual memberships and more effectively serve industry interests. We look forward to working with ECSI in the future.”

About OCP-IP

The OCP International Partnership Association, Inc. (OCP-IP) was announced in December 2001 to promote and support the open core protocol (OCP) as the complete socket standard that ensures rapid creation and integration of interoperable virtual components. OCP-IP’s Governing Steering Committee participants are: Nokia [NYSE: NOK], Texas Instruments [NYSE: TXN], STMicroelectronics [NYSE: STM], United Microelectronics Corporation [NYSE: UMC], Toshiba Semiconductor Group (including Toshiba America TAEC), Sonics, and other industry leading companies. OCP-IP is a non-profit corporation delivering the first fully supported, openly licensed core-centric protocol that comprehensively fulfills system-level integration requirements. The OCP facilitates IP core reusability and reduces design time and risk, along with manufacturing costs for SoC designs. VSIA endorses the OCP socket, and OCP-IP is an Adoption Group of the VSI Alliance. For additional background and membership information, visit www.ocpip.org.

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